RClamp0502BA
Low Capacitance RailClamp®
ESD & CDE Protection

PROTECTION PRODUCTS

Description

RailClamp® TVS diodes are specifically designed to protect sensitive components which are connected to high-speed data and transmission lines from overvoltage caused by ESD (electrostatic discharge), CDE (cable discharge events), and EFT (electrical fast transients).

The RClamp®0502BA has a typical capacitance of only 0.50pF (pin1 to 2). This means it can be used on circuits operating in excess of 3GHz with minimal signal attenuation. They may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (±18kV air, ±12kV contact discharge). Each device can be configured to protect 1 bidirectional line or two unidirectional lines.

These devices are in a small SC-75 (SOT-523) package and feature a lead-free, matte tin finish. They are compatible with both lead free and SnPb assembly techniques. They are designed for use in applications where board space is at a premium. The combination of small size, low capacitance, and high level of ESD protection makes them a flexible solution for applications such as HDMI, MDDI, antenna circuits, Automatic Test Equipment, USB 2.0/3.0, and Infiniband circuits.

Features

- Transient protection for high-speed data lines to
  - IEC 61000-4-2 (ESD) ±18kV (air), ±12kV (contact)
  - IEC 61000-4-4 (EFT) 40A (5/50ns)
  - IEC 61000-4-5 (Surge) 5A (8/20µs)
- Protects up to two I/O lines
- Low capacitance (<1pF)
- No insetion loss to > 3.0 GHz
- Low profile (<1mm)
- Low leakage current and clamping voltage
- Low operating voltage: 5.0V
- Solid-state silicon-avalanche technology

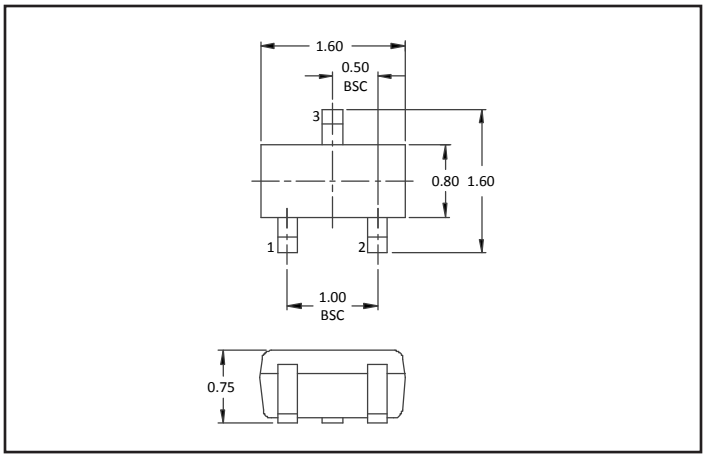
Mechanical Characteristics

- SC-75 (SOT-523) package
- Lead Finish: Matte Tin
- Pb-Free, Halogen Free, RoHS/WEEE Compliant
- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel

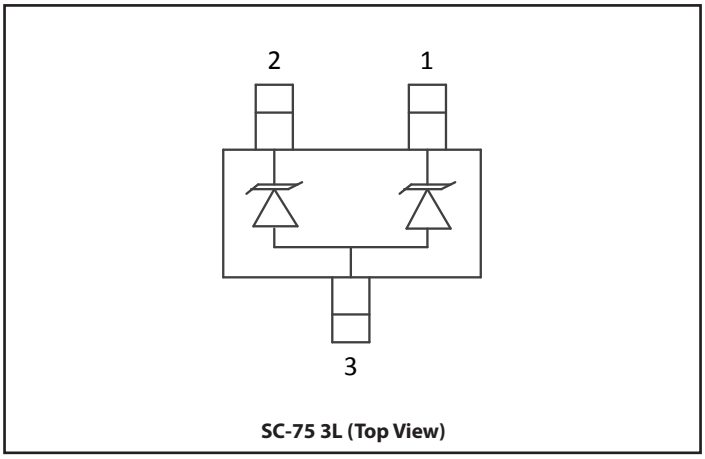
Applications

- Mobile Display Digital Interface (MDDI)
- USB 2.0/USB 3.0
- GaAs Photodetector Protection
- HBT Power Amp Protection
- Infiniband Transceiver Protection

Nominal Dimensions (mm)



Schematic & Pin Configuration



SC-75 3L (Top View)

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20µs)	P_{PK}	125	W
Peak Pulse Current (tp = 8/20µs)	I_{PP}	5	A
ESD per IEC 61000-4-2 (Air)(1) ESD per IEC 61000-4-2 (Contact)(1)	V_{ESD}	±18 ±12	kV
Operating Temperature	T_J	-55 to +125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Characteristics (T=25°C unless otherwise specified)

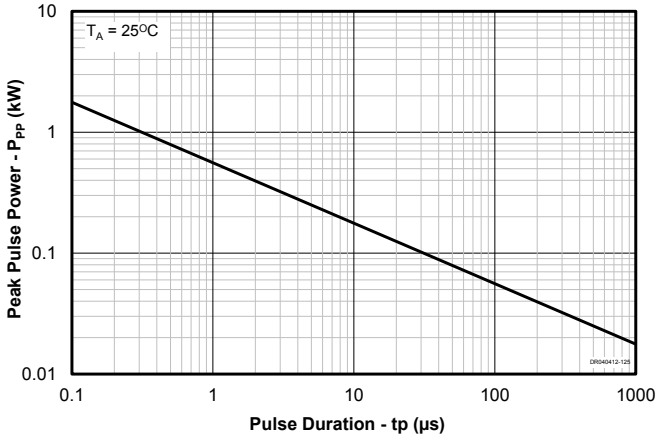
Parameter	Symbol	Conditions		Min.	Typ.	Max.	Units
Reverse Stand-Off Voltage	V_{RWM}	Pin 1 or Pin 2 to Pin 3, and between Pin 1 & 2				5	V
Reverse Breakdown Voltage	V_{BR}	I_{BR} = 1mA, Pin 1 or Pin 2 to Pin 3		6			V
Reverse Leakage Current	I_R	V_{RWM} = 5V, Pin 1 or Pin 2 to Pin 3 and between Pin 1 & 2				1	µA
Clamping Voltage	V_C	t_p = 8/20µs Pin 1 or Pin 2 to Pin 3	I_{PP} = 1A			15	V
		t_p = 8/20µs Pin 1 or Pin 2 to Pin 3	I_{PP} = 5A			22	
		t_p = 8/20µs between Pin 1 & 2	I_{PP} = 5A			25	
Junction Capacitance	C_J	V_R = 0V, f = 1MHz	Pin 1 to Pin 2		0.5	0.9	pF
			Pin 1 or Pin 2 to Pin 3			1.2	pF

Notes:

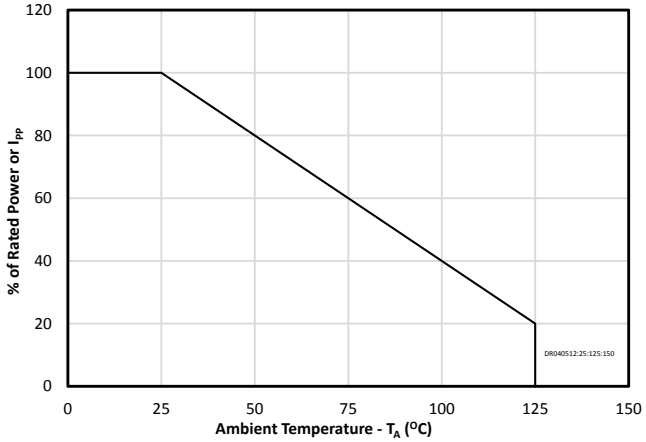
1) ESD gun return path connected to ESD ground plane.

Typical Characteristics

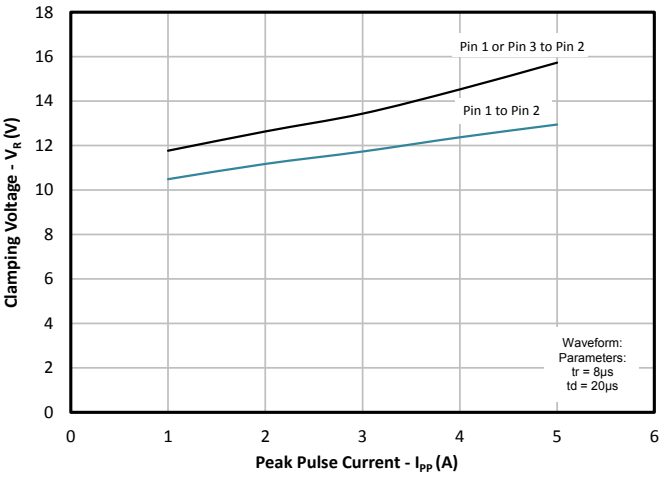
Non Repetitive Peak Pulse Power vs. Pulse Time



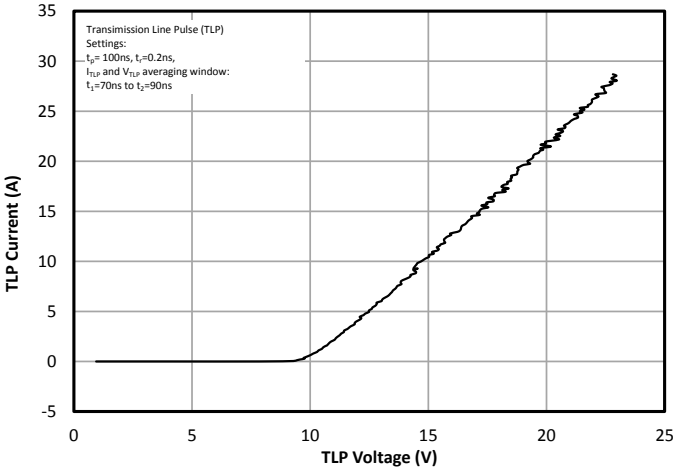
Power Derating Curve



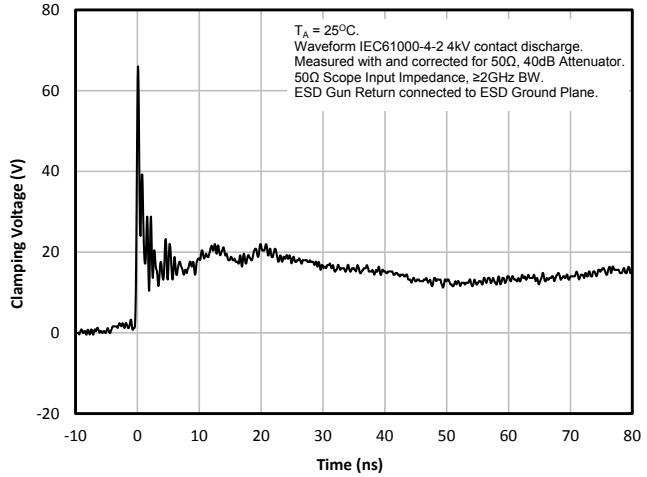
Clamping Voltage vs. Peak Pulse Current (tp=8/20µs)



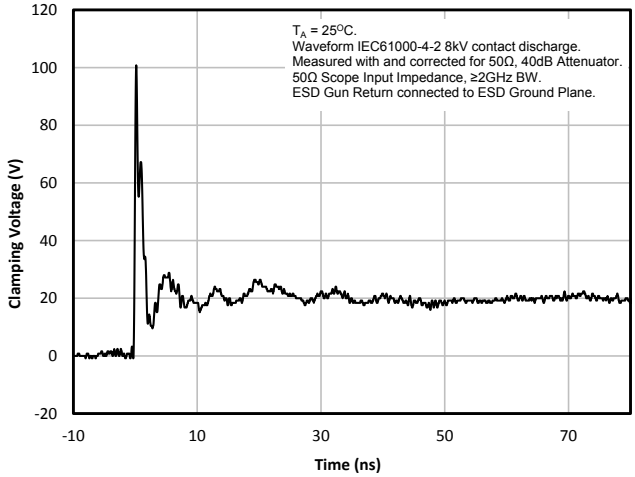
TLP Characteristic



ESD Clamping (4kV Contact per IEC 61000-4-2)

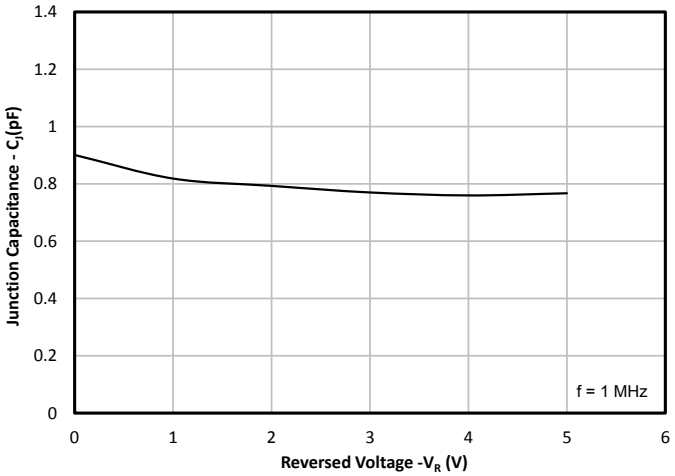


ESD Clamping (8kV Contact per IEC 61000-4-2)

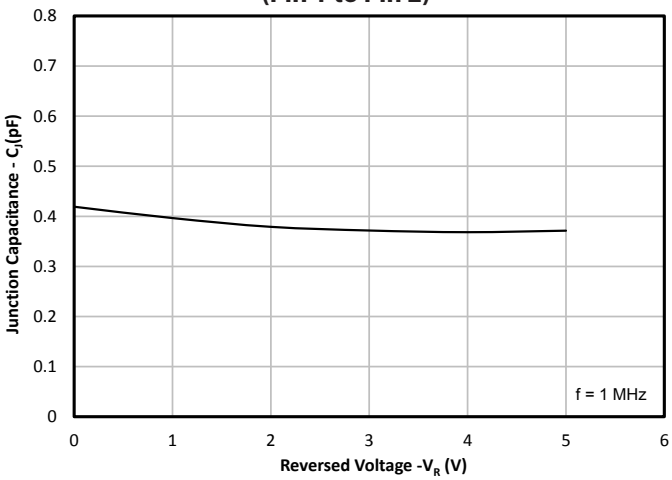


Typical Characteristics (Continued)

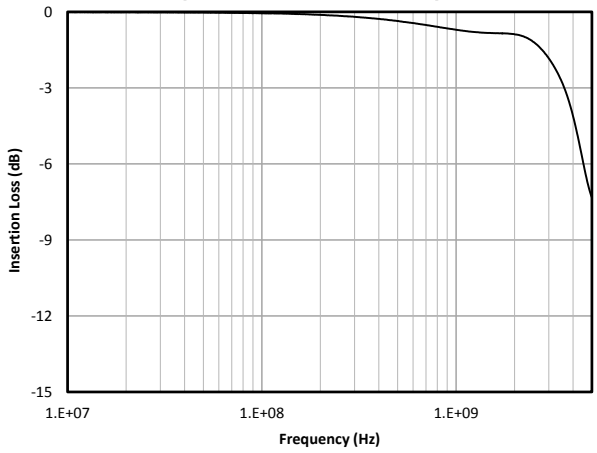
Capacitance vs. Reverse voltage (Pin 1 or Pin 2 to Pin 3)



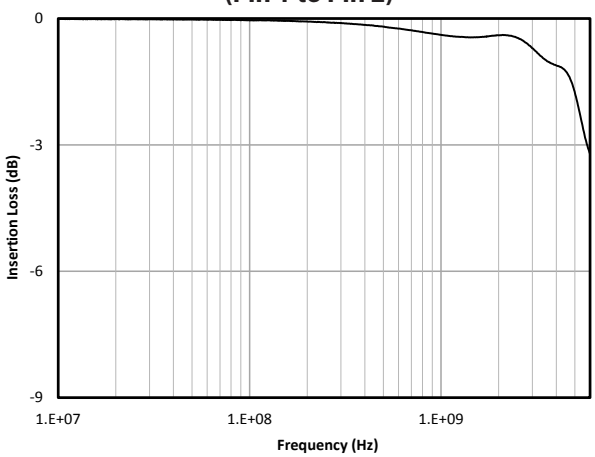
Capacitance vs. Reverse voltage (Pin 1 to Pin 2)



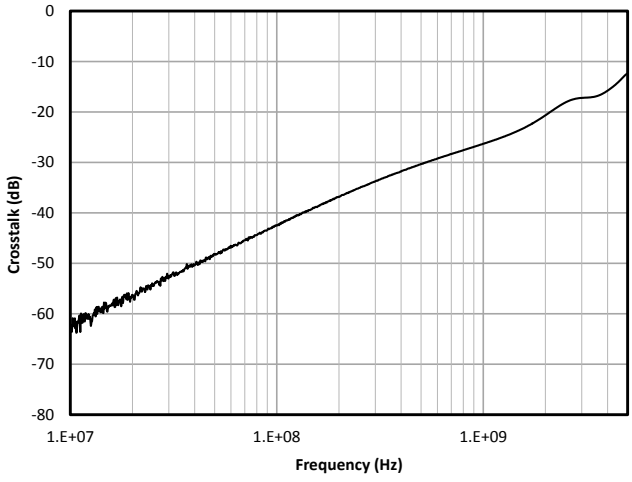
Typical Insertion Loss (Pin 1 or Pin 2 to Pin 3)



Typical Insertion Loss (Pin 1 to Pin 2)



Analog Crosstalk



Application Information

Device Connection Options

This device is optimized for protection of 1 line operating in excess of 3GHz. It may also be used to protect two lines operating in excess of 2.0GHz. The device is connected as follows:

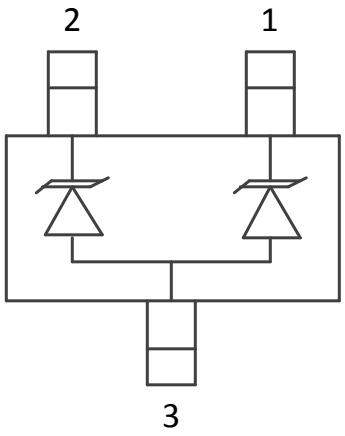
Protection for one line with <1pF capacitance can be achieved by connecting one data line to either pin 1 or pin 2 with the other pin connected to ground. Pin 3 is not connected. The connection to ground should be made directly to a ground plane. The path length should also be kept as short as possible to minimize parasitic inductance.

Protection of two lines is achieved by connecting data lines at pins 1 & 2. Pin 3 is connected to ground. The connection to ground should be made directly to a ground plane. The path length should also be kept as short as possible to minimize parasitic inductance.

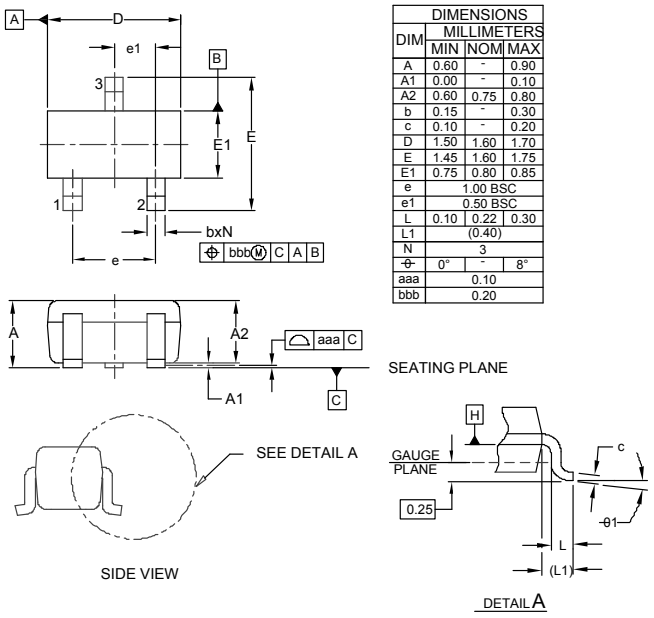
Matte Tin Lead Finish

Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. In addition, unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation of the solder joint.

Figure 1. Pin Configuration



Outline Drawing - SC75 (SOT-523)

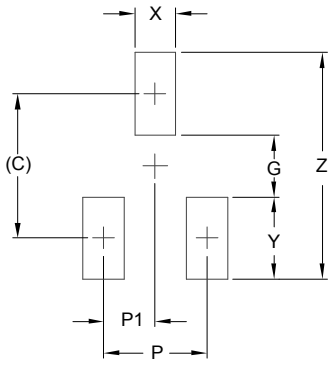


DIMENSIONS			
DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.60	-	0.90
A1	0.00	-	0.10
A2	0.60	0.75	0.80
b	0.15	-	0.30
c	0.10	-	0.20
D	1.50	1.60	1.70
E	1.45	1.60	1.75
E1	0.75	0.80	0.85
e	1.00 BSC		
e1	0.50 BSC		
L	0.10	0.22	0.30
L1	(0.40)		
N	3		
θ	0°	-	8°
aaa	0.10		
bbb	0.20		

NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-
3. DIMENSIONS "E1" AND "D" DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

Land Pattern - SC75 (SOT-523)

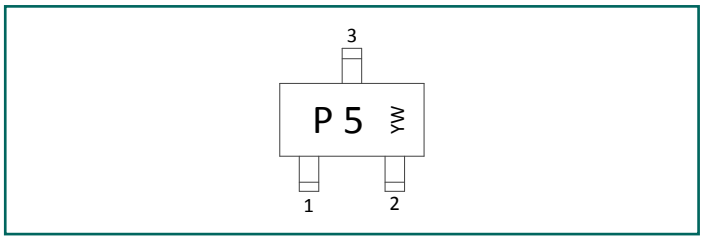


DIMENSIONS	
DIM	MILLIMETERS
C	(1.40)
G	0.60
P	1.00
P1	0.50
X	0.40
Y	0.80
Z	2.20

NOTES:

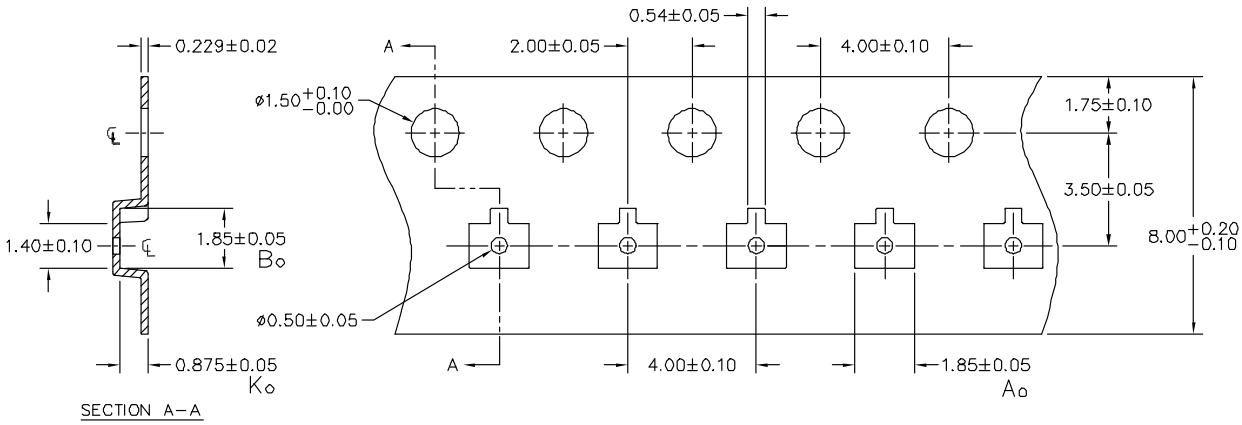
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

Marking Code

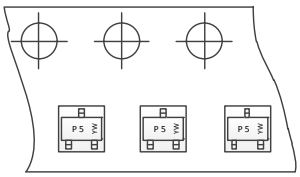


YW = Date Code

Tape and Reel Specification



NOTES: 1.) ALL DIMENSIONS IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.



Ordering Information

Part Number	Qty per Reel	Reel Size
RClamp0502BATCT	3,000	7”

Contact Information

Semtech Corporation
200 Flynn Road, Camarillo, CA 93012
Phone: (805) 498-2111, Fax: (805) 498-3804
www.semtech.com

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